

April 2009

FOD073L LVTTL/LVCMOS Compatible Low Input Current High Gain Split Darlington Optocoupler

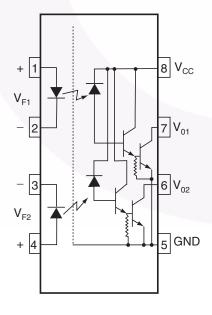
Features

- Low power consumption
- Low input current: 0.5mA
- Dual channel 8-pin SOIC package
- High CTR: 400% minimum
- High CMR: 10kV/µs
- Guaranteed performance over temperature 0°C to 70°C
- U.L. recognized (File # E90700)
- LVTTL/LVCMOS Compatible output

Applications

- Digital logic ground isolation LVTTL/LVCMOS
- Telephone ring detector
- EIA-RS-232C line receiver
- High common mode noise line receiver
- µP bus isolation
- Current loop receiver

Schematic



Description

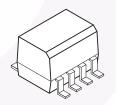
The FOD073L optocoupler consists of an AlGaAs LED optically coupled to a high gain split darlington photodetector. This device is specified to operate at a 3.3V supply voltage.

An integrated emitter – base resistor provides superior stability over temperature.

The combination of a very low input current of 0.5mA and a high current transfer ratio of 2000% (typical) makes this device particularly useful for input interface to MOS, CMOS, LSTTL and EIA RS232C, while output compatibility is ensured to LVCMOS as well as high fan-out LVTTL requirements.

An internal noise shield provides exceptional common mode rejection of 10kV/µs.

Package Outline



Truth Table

| LED | vo |
|-----|------|
| ON | LOW |
| OFF | HIGH |

Absolute Maximum Ratings (No derating required up to 85°C)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Parameter | | | | |
|------------------------|--|--------------|----------------|----|--|--|
| T _{STG} | Storage Temperature | | -40 to +125 | °C | | |
| T _{OPR} | Operating Temperature | | -40 to +85 | °C | | |
| T _{SOL} | Lead Solder Temperature (Wave solder only. See reflow profile for surface mou | nt devices) | 260 for 10 sec | °C | | |
| EMITTER | | | | | | |
| I _F (avg) | DC/Average Forward Input Current | Each Channel | 20 | mA | | |
| I _F (pk) | Peak Forward Input Current (50% duty cycle, 1ms P.W.) | Each Channel | 40 | mA | | |
| I _F (trans) | Peak Transient Input Current (≤1µs P.W., 300 pps) | Each Channel | 1.0 | А | | |
| V _R | Reverse Input Voltage | Each Channel | 5 | V | | |
| PD | Input Power Dissipation | Each Channel | 35 | mW | | |
| DETECTOR | | | <u> </u> | | | |
| l _O (avg) | Average Output Current | Each Channel | 60 | mA | | |
| V _{EB} | Emitter-Base Reverse Voltage (FOD070L, FOD270L) | Each Channel | 0.5 | V | | |
| V_{CC}, V_O | Supply Voltage, Output Voltage | Each Channel | -0.5 to 7 | V | | |
| PD | Output power dissipation | Each Channel | 100 | mW | | |

Electrical Characteristics ($T_A = 0$ to 70°C unless otherwise specified)

Individual Component Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ.* | Max. | Unit |
|------------------|------------------------------------|--|------|-------|------|------|
| EMITTER | | | | | | |
| V _F | Input Forward Voltage | T _A =25°C | | 1.35 | 1.7 | V |
| | | I _F = 1.6mA (Each Channel) | | | 1.75 | |
| BV _R | Input Reverse Breakdown Voltage | T _A =25°C, I _R = 10μA (Each Channel) | 5.0 | | | V |
| DETECTO | DR | | | | | |
| I _{OH} | Logic High Output Current | $I_F = 0 \text{ mA}, V_O = V_{CC} = 3.3 \text{V}$ (Each Channel) | | 0.05 | 25 | μA |
| I _{CCL} | Logic Low Supply Current | $I_{F1} = I_{F2} = 1.6 \text{mA},$ $V_{O1} = V_{O2} = \text{Open}, V_{CC} = 3.3 \text{V}$ | | 0.8 | 3 | mA |
| ICCH | Logic High Supply Current | $I_{F1} = I_{F2} = 0mA,$ $V_{O1} = V_{O2} = Open, V_{CC} = 3.3V$ | | 0.01 | 2 | μA |

Transfer Characteristics

| Symbol | Parameter | | Test Conditions | Min. | Тур.* | Max. | Unit |
|-----------------|---|------------------|--|------|-------|------|------|
| CTR | COUPLED Current Transfer Ratio (Note 1) | I _F = | 0.5mA, V _O = 0.4V, V _{CC} = 3.3V | 400 | | 7000 | % |
| V _{OL} | Logic Low Output Voltage | I _F = | $1.6mA, I_{O} = 8mA, V_{CC} = 3.3V$ | | 0.07 | 0.3 | V |
| | | I _F = | 5mA, I_{O} = 15mA, V_{CC} = 3.3V | | 0.07 | 0.4 | |

Switching Characteristics (V_{CC} = 3.3 V)

| Symbol | Parameter | Test Conditions | Min. | Тур.* | Max. | Unit |
|--------------------|---|--|-------|--------|------|------|
| T _{PHL} | Propagation Delay Time to Logic LOW | $\begin{array}{l} R_{L}=4.7\mathrm{k}\Omega,\ I_{F}=0.5\mathrm{m}A\\ (Fig.~9) \end{array}$ | | 5 | 30 | μs |
| T _{PLH} | Propagation Delay Time to Logic HIGH | $R_L = 4.7$ kΩ, $I_F = 0.5$ mA (Fig. 9) | | 25 | 90 | μs |
| ICM _H I | Common Mode Transient Immunity at Logic HIGH | $ I_{F} = 0 \text{ mA, } V_{CM} = 10 V_{P-P}, T_{A} = 25^{\circ}\text{C}, \\ R_{L} = 2.2 \text{k}\Omega \text{ (Note 2) (Fig. 10)} $ | 1,000 | 10,000 | | V/µs |
| ICMLI | Common Mode Transient Immunity at Logic LOW | $\begin{split} I_{\text{F}} &= 1.6\text{mA}, V_{\text{CM}} = 10 \; V_{\text{P-P}}, \; \text{R}_{\text{L}} = 2.2 \text{k} \Omega, \\ T_{\text{A}} &= 25^{\circ}\text{C} \; \; (\text{Note 2}) \; (\text{Fig. 10}) \end{split}$ | 1,000 | 10,000 | | V/µs |

*All typicals at $T_A = 25^{\circ}C$

Electrical Characteristics (Continued) ($T_A = 0$ to 70°C unless otherwise specified)

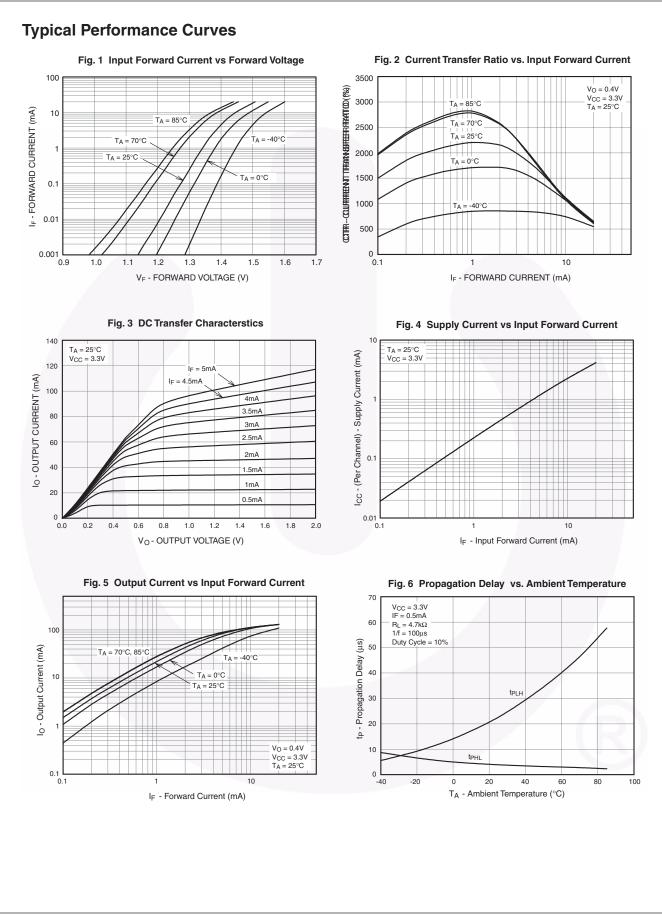
Isolation Characteristics

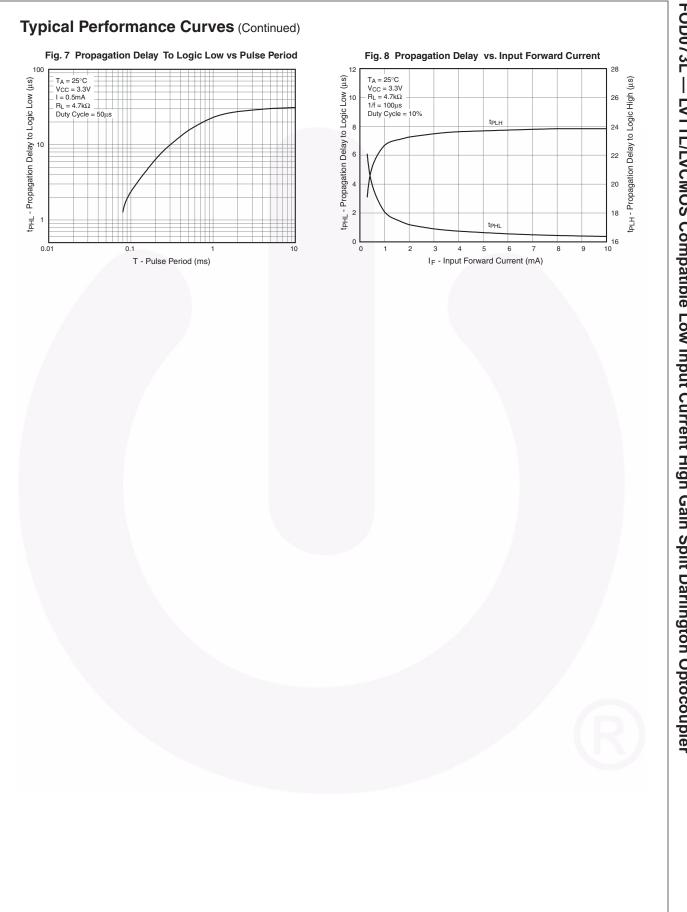
| Symbol | Characteristics | Test Conditions | Min. | Тур.* | Max. | Unit |
|------------------|--|--|-------|------------------|------|------------------|
| I _{I-O} | Input-Output Insulation Leakage Current | Relative humidity = 45%, $T_A = 25^{\circ}C$, t = 5 s, $V_{I-O} = 3000$ VDC (Note 3) | | | 1.0 | μA |
| V _{ISO} | Withstand Insulation Test Voltage | $\label{eq:rescaled} \begin{array}{l} R_{H} \leq 50\%, T_{A} = 25^{\circ}C, I_{I-O} \leq 2\mu A, \\ t = 1 \mbox{ min. (Note 3)} \end{array}$ | 2500 | | | V _{RMS} |
| R _{I-O} | Resistance (Input to Output) | V _{I-O} = 500 VDC (Note 3) | | 10 ¹² | | Ω |
| C _{I-O} | Capacitance (Input to Output) | f = 1 MHz (Notes 3, 4) | | 0.7 | | pF |
| I _{I-I} | Input-Input Insulation Leakage Current | $RH \le 45\%$, $V_{I-I} = 500 VDC$ (Note 5) | 0.005 | | | μA |
| R _{I-I} | Input-Input Resistance | V _{I-I} = 500 VDC (Note 5) | | 10 ¹¹ | | Ω |
| C _{I-I} | Input-Input Capacitance | f = 1 MHz (Note 5) | | 0.03 | | pF |

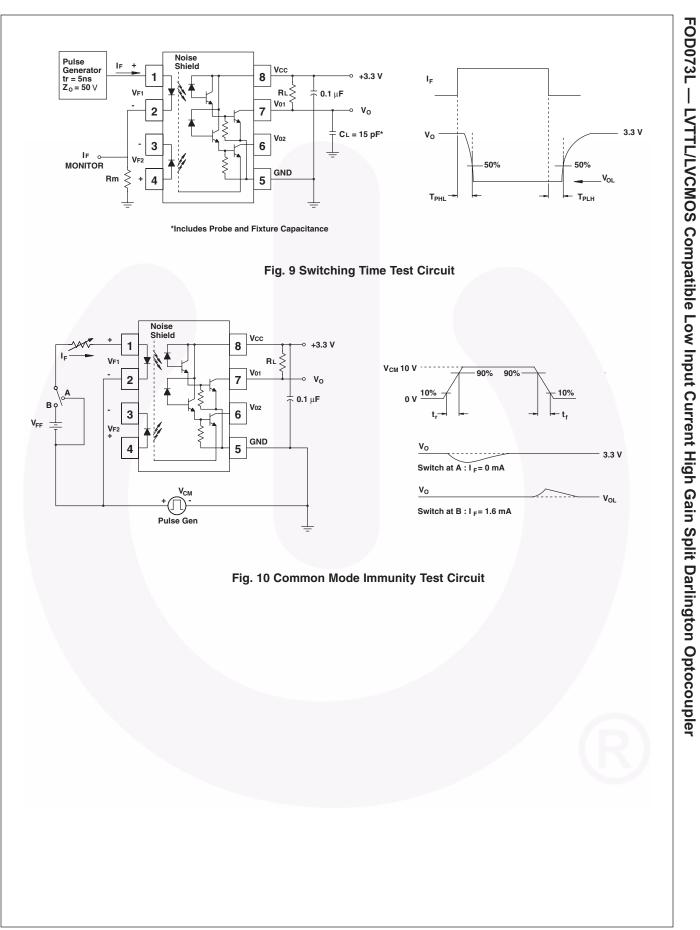
*All typicals at $T_A = 25^{\circ}C$

Notes:

- 1. Current Transfer Ratio is defined as a ratio of output collector current, I_O, to the forward LED input current, I_F times 100%.
- 2. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8 V$).
- 3. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
- 4. CI-O is measured by shorting pins 1 and 2 or pins 3 and 4 together and pins 5 through 8 shorted together.
- 5. Measured between pins 1 and 2 shorted together, and pins 3 and 4 shorted together.



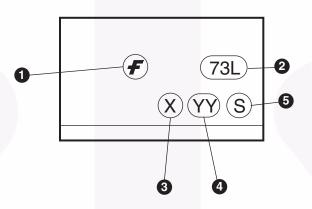




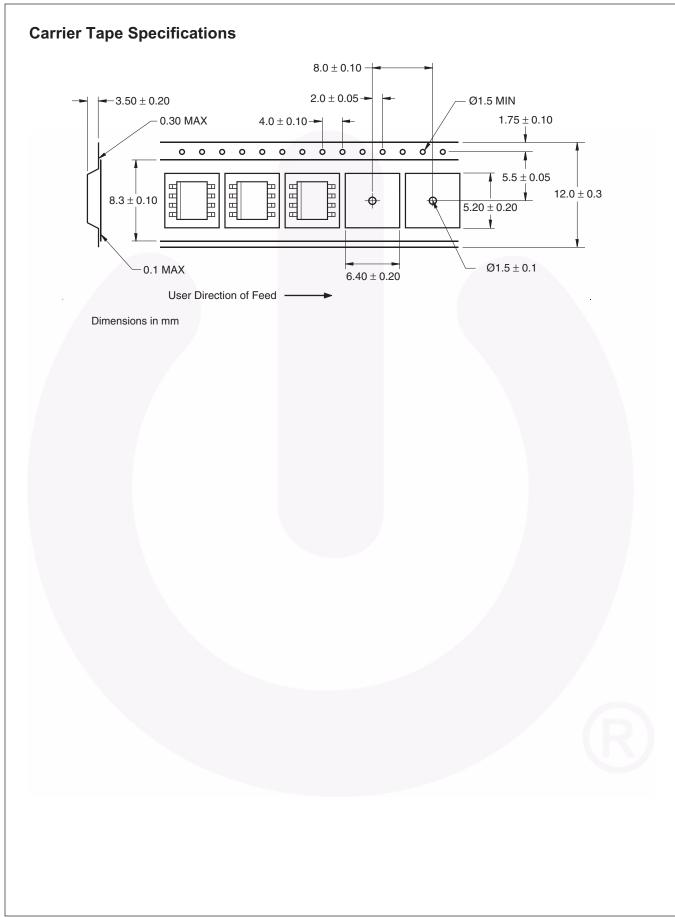
Ordering Information

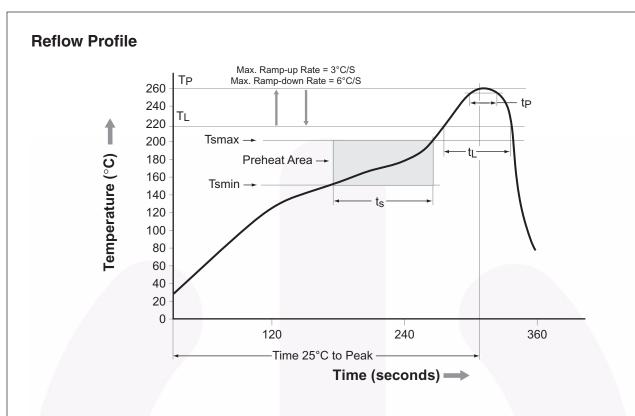
| Option | Order Entry Identifier | Description |
|-----------|---------------------------|--------------------------------------|
| No Suffix | FOD073L | Shipped in tubes (50 units per tube) |
| R2 | FOD073LR2 | Tape and reel (2,500 units per reel) |

Marking Information

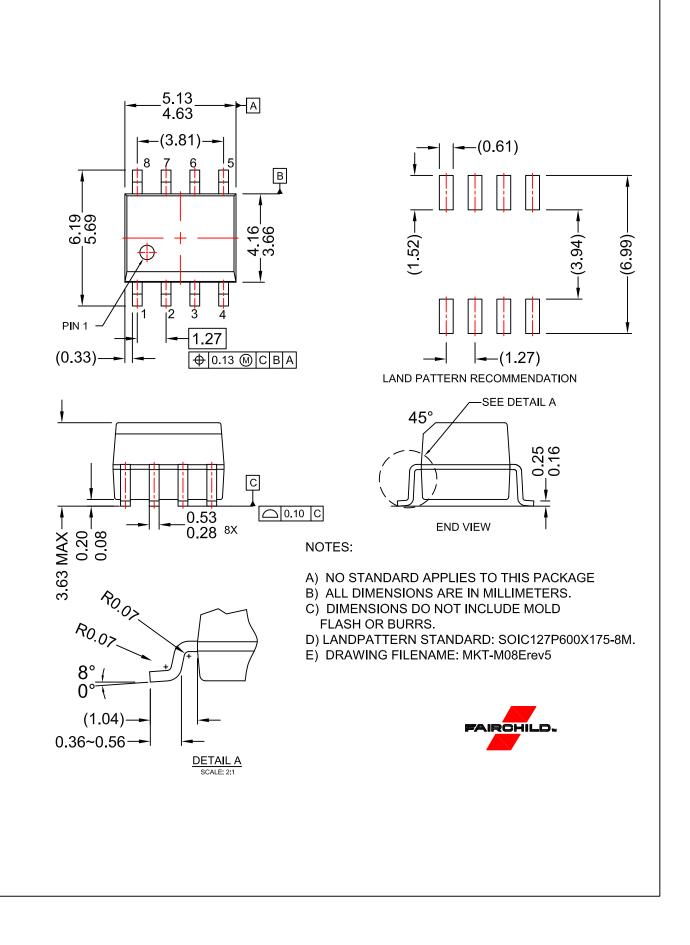


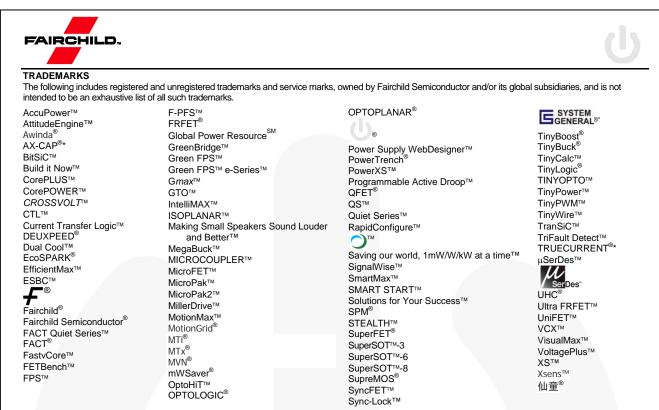
| | Definitions | | | | | |
|---|---|--|--|--|--|--|
| 1 | Fairchild logo | | | | | |
| 2 | Device number | | | | | |
| 3 | One digit year code, e.g., '3' | | | | | |
| 4 | Two digit work week ranging from '01' to '53' | | | | | |
| 5 | Assembly package code | | | | | |





| Profile Freature | Pb-Free Assembly Profile | | |
|--|--------------------------|--|--|
| Temperature Min. (Tsmin) | 150°C | | |
| Temperature Max. (Tsmax) | 200°C | | |
| Time (t _S) from (Tsmin to Tsmax) | 60–120 seconds | | |
| Ramp-up Rate (t _L to t _P) | 3°C/second max. | | |
| Liquidous Temperature (T _L) | 217°C | | |
| Time (t_L) Maintained Above (T_L) | 60–150 seconds | | |
| Peak Body Package Temperature | 260°C +0°C / -5°C | | |
| Time (t _P) within 5°C of 260°C | 30 seconds | | |
| Ramp-down Rate (T _P to T _L) | 6°C/second max. | | |
| Time 25°C to Peak Temperature | 8 minutes max. | | |





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